

SOT1097-2

plastic low profile ball grid array package; 228 balls

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	LBGA228
Package type industry code	LBGA228
Package style descriptive code	LBGA (low profile ball grid array)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
IEC package outline code	---
JEDEC package outline code	---
JEITA package outline code	---
Mounting method type	S (surface mount)
Issue date	1-12-2009

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	16.8	-	17	17.2	mm
E	package width	16.8	-	17	17.2	mm
A	seated height	1.15	-	1.36	1.5	mm
A ₂	package height	0.85	-	1.01	1.1	mm
e	nominal pitch	-	-	1	-	mm
n ₂	actual quantity of termination	-	-	228	-	



2. Package outline

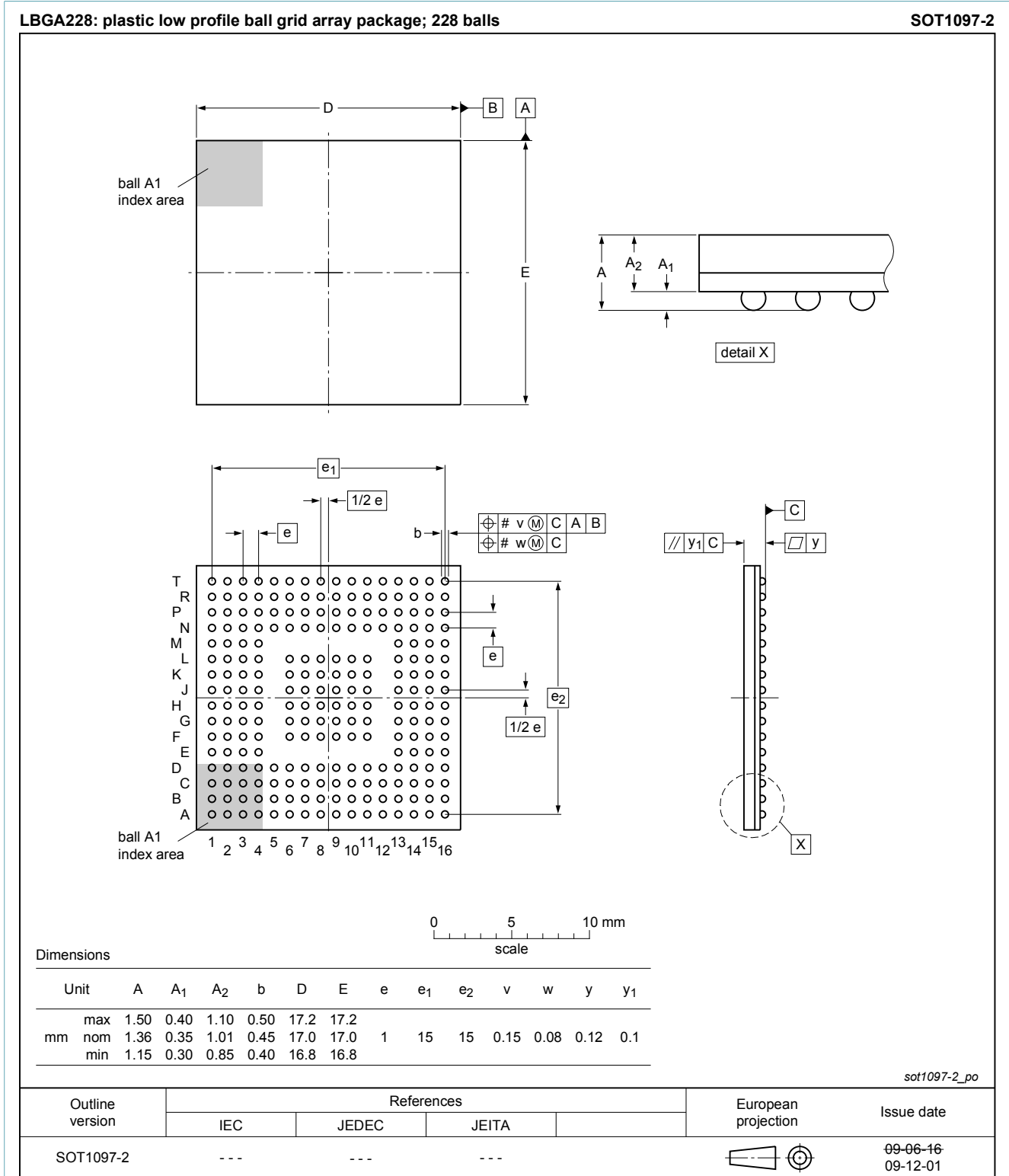


Fig. 1. Package outline LPGA228 (SOT1097-2)

3. Legal information

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Date of release: 8 February 2016
